

Fraunhofer project center in Tohoku University



FhG Germany – Sendai city partnership signing ceremony in Munich (July15,2005)



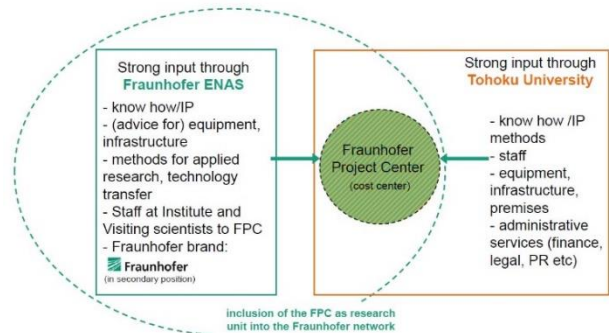
1st Fraunhofer Symposium in Sendai (Oct.19, 2005)



FhG Germany – WPI-AIMR Tohoku Univ. partnership signing ceremony in Sendai (Nov. 8, 2011)

Fraunhofer Project Center Model

Key aspects of cooperation – Mutual contributions



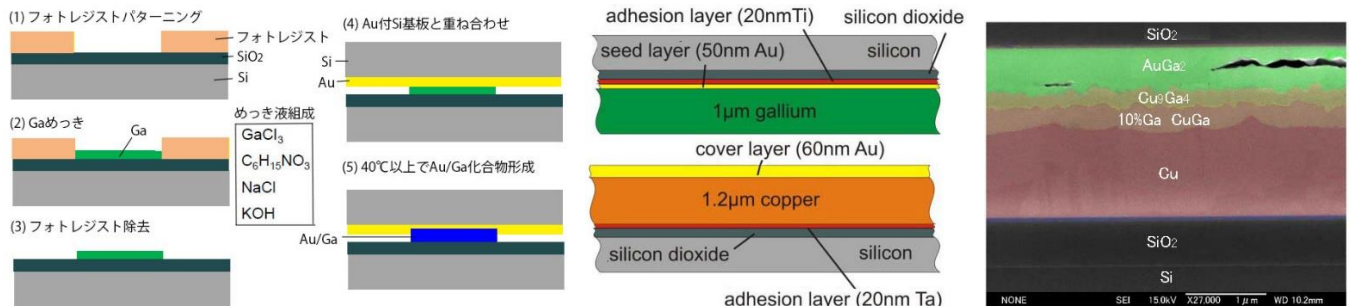
FhG Project center in WPI-AIMR, Tohoku Univ. (April 1, 2012)



Assoc. Prof. Joerg .FrÖmel



Dr. Nguyen Mai Phuong



Low temperature SLID (Solid-Liquid Inter-Diffusion) bonding with Cu- Ga

(J.Froemel et.al. (ENAS, Fh.G), J. of Microelectromechanical Systems, 24 (2015) 1973)

Old method to fill an eroded tooth (amalgam method) (UV curable resin at present)
 Cu powder + Hg → Solidify (Metallic compound)